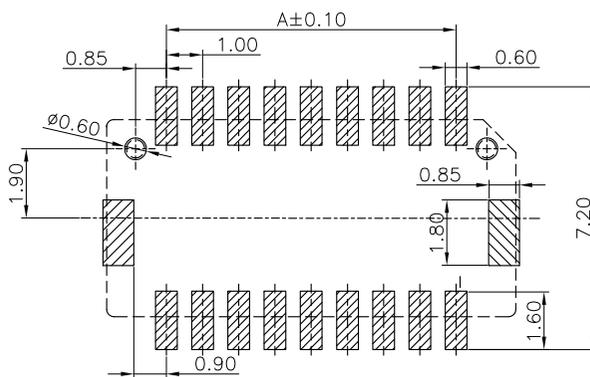
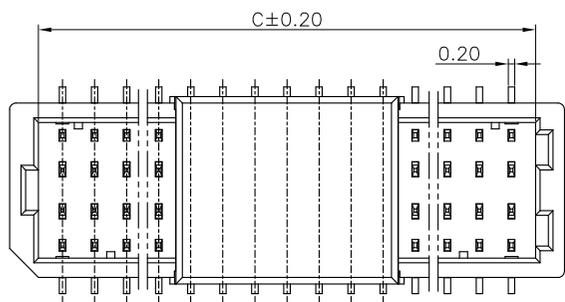
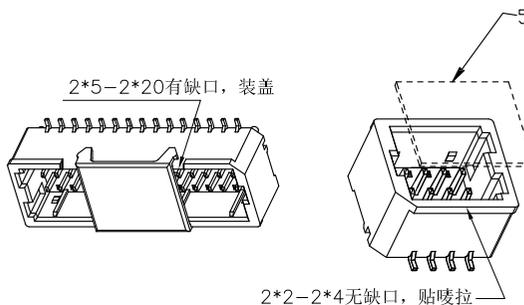
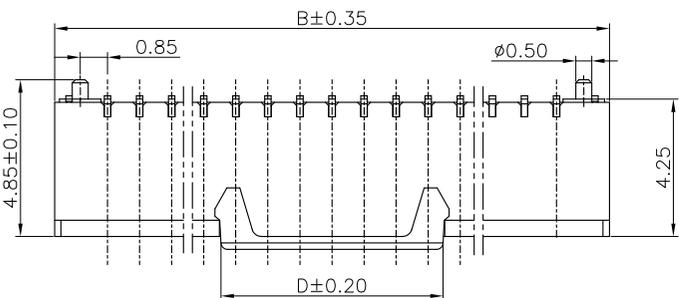
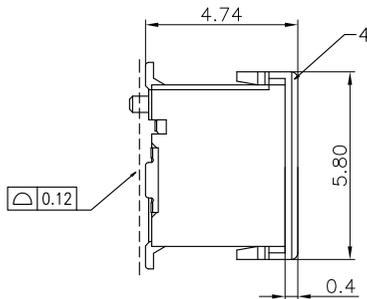
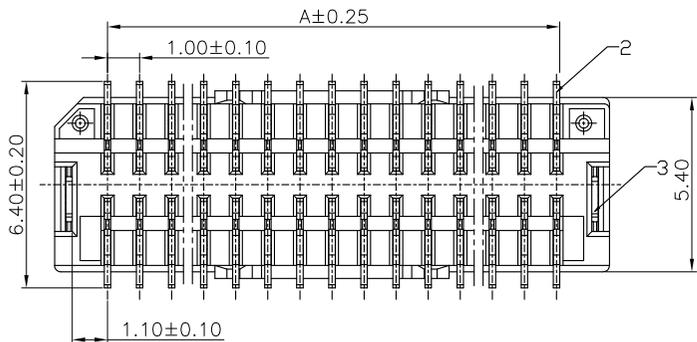


The product using material and processing must conform to the "WI-PZ-001"HSF technical standard control requirements



PCB LAYOUT

NOTE:

- MATERIAL SPECIFICATION:
 - 1-1.HOUSING: PA9T,UL94V-0
 - 1-2.CONTACTS: PHOSPHOR BRONZE
 - 1-3.SOLDER TAB: BRASS
 - 1-4.COVER: PA9T,UL94V-0
- PLATING SPECIFICATION:
 - 2-1.CONTACTS: TIN/GOLD FLASH PLATED OVER ALL.
 - 2-2.SOLDERING LUG: TIN/GOLD FLASH PLATED OVER ALL.
- MECHANICAL PERFORMANCE:
 - 3-1.RETENTIVITY FORCE: 0.5kgf/pin min
 - 3-2.DURABILITY: 30 CYCLES.
- ELECTRICAL PERFORMANCE:
 - 4-1.CURRENT RATING: 1A
 - RATED VOLTAGE : 50V AC/DC
 - 4-2.CONTACT RESISTANCE: 20 mΩ MAX
 - 4-3.INSULATION RESISTANCE: 100MΩ Min
 - 4-4.DIELECTRIC WITHSTANDING : 500V
- ENVIRONMENTAL PERFORMANCE:
 - 5-1.OPERATING TEMPERATURE: -25°C~+85°C.
- PACKAGE SPEC: REEL
- P/N:

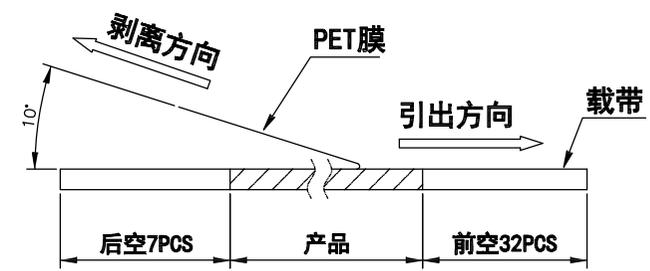
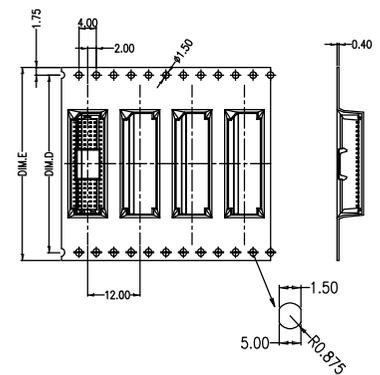
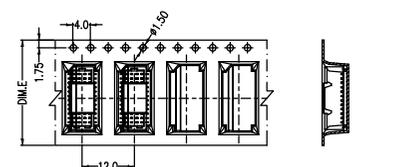
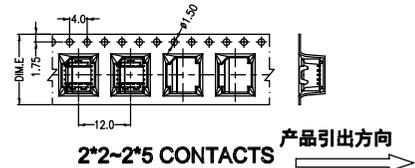
A1003 W 0-2 XX 2 X X 0
 SERIES NO: _____ COLOR: A-BLACK S-NATURE
 CONNECTOR: W-WAFER
 ANGLE: 0-180°
 ROW NO: 2-DOUBLE ROW
 PIN Q'PY: 04~50
 PLATING: A-ALL AU G/F C-BRIGHE TIN D-FOG TIN
 TERMIPOINT: 2-SMT

Circuit	Dimensions(mm)				Circuit	Dimensions(mm)			
	A	B	C	D		A	B	C	D
2*02	1.00	4.30	2.50	Mylar	2*11	10.00	13.30	11.50	
2*03	2.00	5.30	3.50		2*12	11.00	14.30	12.50	
2*04	3.00	6.30	4.50		2*13	12.00	15.30	13.50	
2*05	4.00	7.30	5.50		2*14	13.00	16.30	14.50	
2*06	5.00	8.30	6.50		2*15	14.00	17.30	15.50	
2*07	6.00	9.30	7.50		2*16	15.00	18.30	16.50	
2*08	7.00	10.30	8.50		2*18	17.00	20.30	18.50	
2*09	8.00	11.30	9.50		2*20	19.00	22.30	20.50	
2*10	9.00	12.30	10.50		2*25	24.00	27.30	25.50	

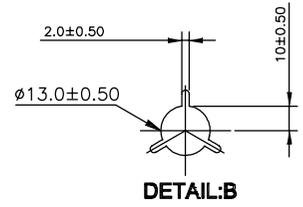
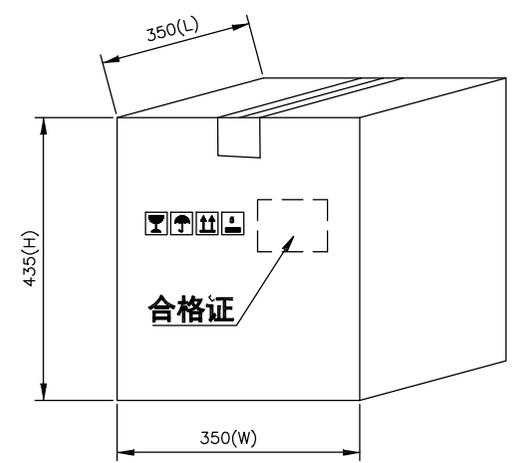
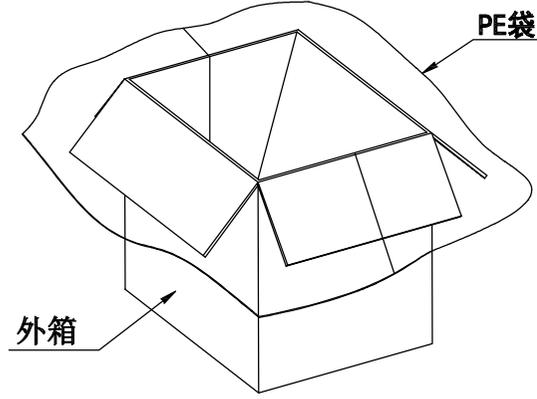
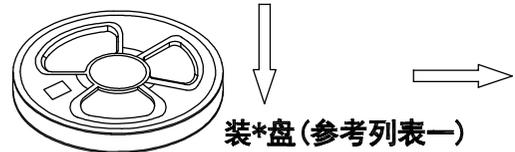
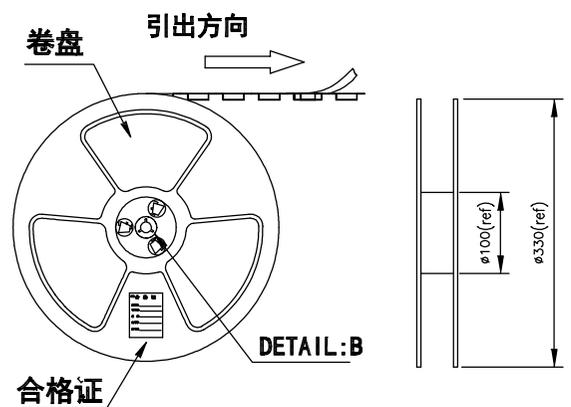
REV.	REVISION RECORD	DATE	GENERAL TOLERANCES		SCALE:	NAME	DATE	PART.NO: A1003W0-2XX2XX0	DWG.NO: ENDE05	万连科技 WanLian Technology Co., Ltd
A0	NEW RELEASE	21.10.12	LINEAR	ANGLES	1:1	Wang_jr	23.09.25			
A1	PART NUMBER RENEWAL	23.09.25	0.0±0.35	X'REF±6°	APPROVED	Han_Gao	23.09.25			
			0.00±0.25	X'±3°	DESIGNER	Zijun_Huang	23.09.25			
			UNIT: mm	0.00±0.10	X'X' ±2'	DRAWN		TITLE: Pitch 1.00mm 180°SHD 双排立贴带柱带吸附盖Wafer	REV: A1	SHEET: 1/2

The product using material and processing must conform to the "WI-PZ-001" HSF technical standard control requirements

RoHS



(PET膜剥离示意图)



列表一

Circuits	DIM. D	DIM. E	Q'ty/Reel	Packing (Reel/Caton)
2*2~2*5PIN	—	16	1000PCS	20/Reel
2*6~2*12PIN	—	24	1000PCS	15/Reel
2*14~2*16PIN	—	32	1000PCS	11/Reel
2*20~2*25PIN	40.5	44	1000PCS	8/Reel

包装说明:
1. 把成品包入卷盘中, 每盘装1000PCS, 卷盘上贴上合格证, 将装好产品的卷盘放进外箱中, 外箱内先套一个大PE袋, 外箱上贴贴上合格证.
2. 所有材料有害物控制需符合RoHS标准。

REV.	REVISION RECORD	DATE	GENERAL TOLERANCES		SCALE:	NAME	DATE	PART.NO:	DWG.NO:	 WanLian Technology Co., Ltd REV: A1 SHEET: 2/2
AO	NEW RELEASE	21.10.12		LINEAR	1:1	Wang_jr	23.09.25	A1003W0-2XX2XX0	ENDE05	
A1	PART NUMBER RENEWAL	23.09.25		ANGLES	APPROVED	Han_Gao	23.09.25			
			UNIT: mm	0.00±0.25	X'±3'	DESIGNER	Zijun_Huang	TITLE:	包装图	
			SIZE: A4	0.000±0.10	X'X' ±2'	DRAWN				